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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10018188	FILING DATE 12/18/2001	CLASS 451	SUBCLASS 041	GAU 0723	EXAMINER Eley
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3724

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****CONTINUING DATA VERIFIED:**
THIS APPLICATION IS A 371 OF PCT/JP00/03891 06/15/2000

**** FOREIGN APPLICATIONS VERIFIED:**
JAPAN 172821/1999 06/18/1999
JAPAN 204842/1999 07/19/1999
JAPAN 332221/1999 11/24/1999

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO 511.40998X00

TITLE : Abrasive compound for cmp, method for polishing substrate and method for manufacturing semiconductor device using the same, and additive for cmp abrasive compound

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
ISSUE FEE Amount Due Date Paid		Assistant Examiner	
		Primary Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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CLAIMS ALLOWED	
Total Claims	Print Claim for O.G.
DRAWING	
Sheets Drawg.	Print Fig.
Application Examiner	

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